

## General Description

The QM01N65L is the highest performance N-ch MOSFETs with extreme high cell density , which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The QM01N65L meet the RoHS and Green Product requirement , 100% EAS guaranteed with full function reliability approved.

## Features

- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	650	V
$V_{GS}$	Gate-Source Voltage	$\pm 30$	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	0.2	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^1$	0.15	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	1	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation <sup>4</sup>	0.89	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

## Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient (Steady State) <sup>1</sup>	---	140	°C/W

## Product Summary

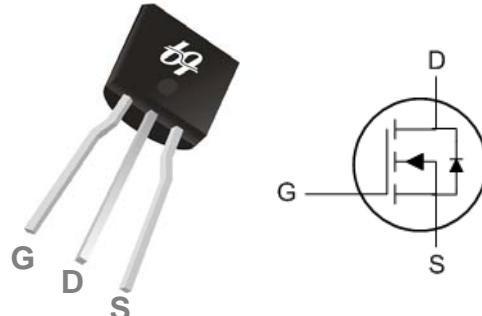


BVDSS	RDS(on)	ID
650V	12 Ω	0.2A

## Applications

- High efficient switched mode power supplies
- Electronic lamp ballast
- LCD TV/ Monitor
- Adapter

## TO-92 Pin Configuration



**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	650	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.63	---	$\text{V}/^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=10\text{V}$ , $I_D=0.15\text{A}$	---	10.5	12	$\Omega$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	2	---	5	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D=250\mu\text{A}$	---	-7.4	---	$\text{mV}/^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=520\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	2	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 30\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	nA
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=5\text{V}$ , $I_D=0.15\text{A}$	---	0.31	---	S
$R_g$	Gate Resistance	$V_{\text{DS}}=0\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	4.9	9.8	$\Omega$
$Q_g$	Total Gate Charge (10V)		---	6.03	8.4	nC
$Q_{\text{gs}}$	Gate-Source Charge	$V_{\text{DS}}=520\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=1\text{A}$	---	1.95	2.7	
$Q_{\text{gd}}$	Gate-Drain Charge		---	2.3	3.2	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time		---	4.4	8.8	ns
$T_r$	Rise Time	$V_{\text{DD}}=300\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=10\Omega$ ,	---	18.4	33	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time	$I_D=1\text{A}$	---	7.2	14.4	
$T_f$	Fall Time		---	22.4	45	
$C_{\text{iss}}$	Input Capacitance		---	175	245	pF
$C_{\text{oss}}$	Output Capacitance	$V_{\text{DS}}=25\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	17.8	25	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	4.3	6	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,6</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	0.2	A
$I_{\text{SM}}$	Pulsed Source Current <sup>2,6</sup>		---	---	1	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V
$t_{\text{rr}}$	Reverse Recovery Time		---	181	---	nS
$Q_{\text{rr}}$	Reverse Recovery Charge	$I_F=1\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ , $T_J=25^\circ\text{C}$	---	336	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 4.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

### Typical Characteristics

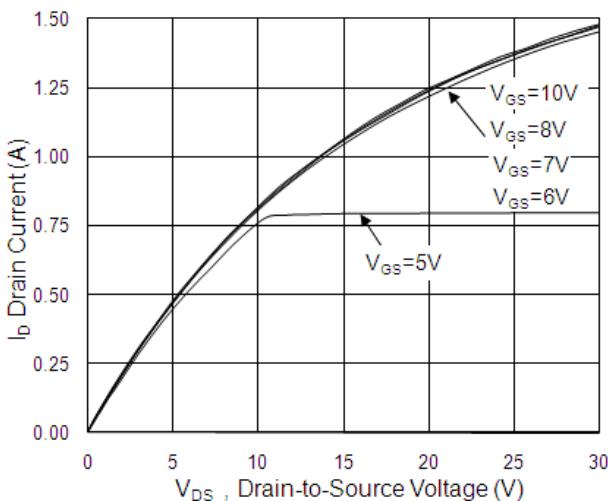


Fig.1 Typical Output Characteristics

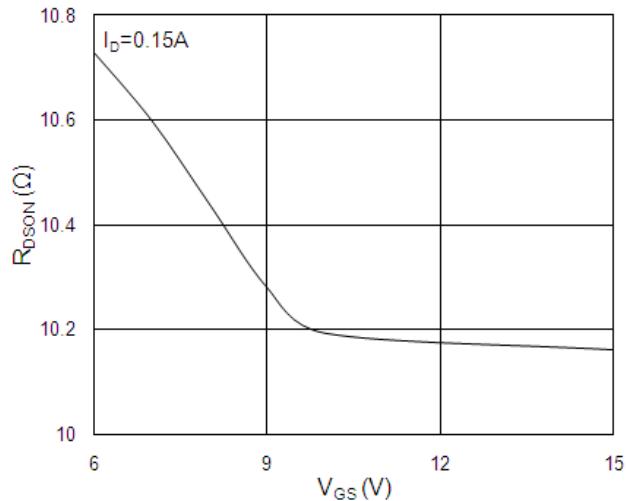


Fig.2 On-Resistance vs. G-S Voltage

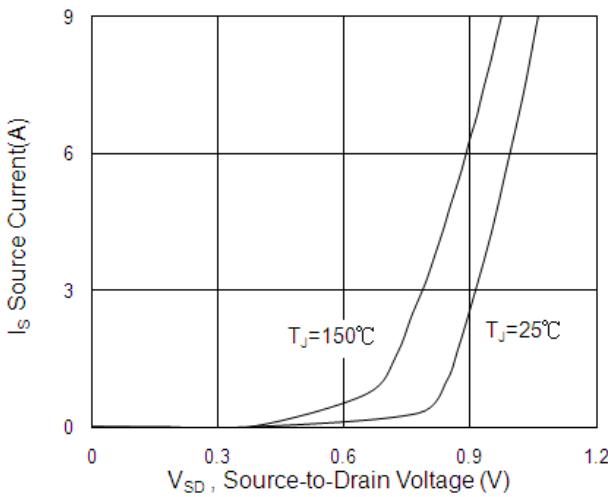


Fig.3 Forward Characteristics of Reverse

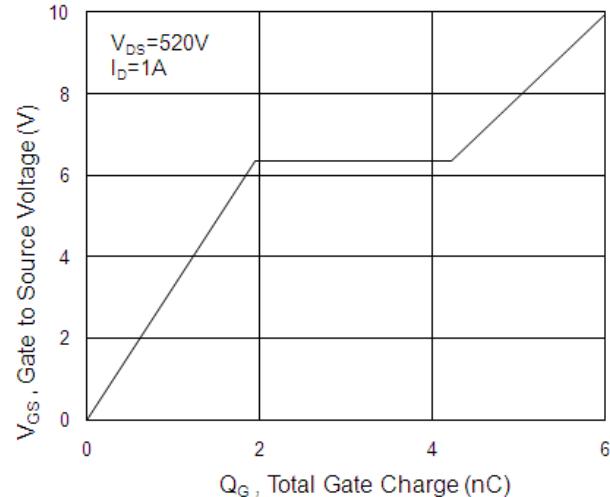


Fig.4 Gate-Charge Characteristics

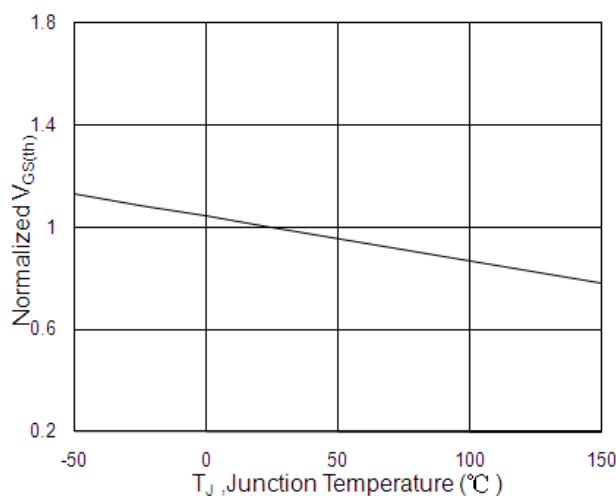


Fig.5  $V_{GS(th)}$  vs.  $T_J$

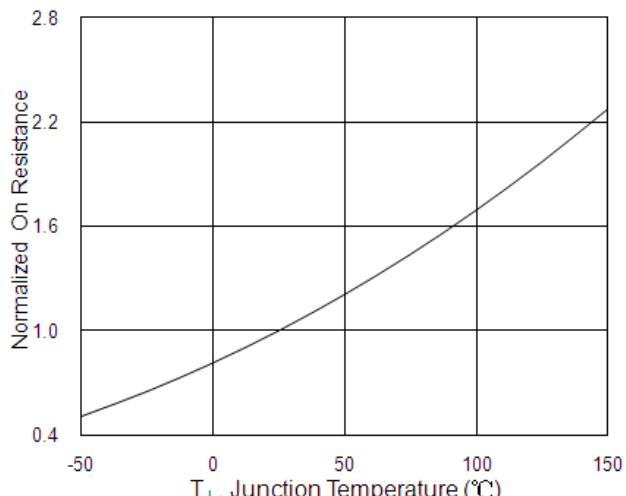
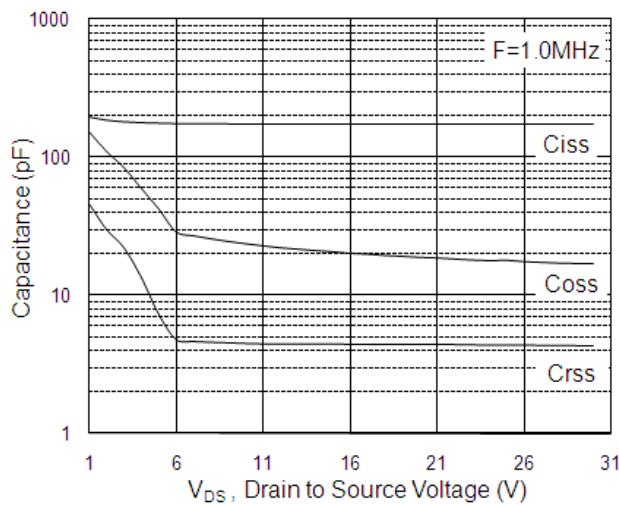
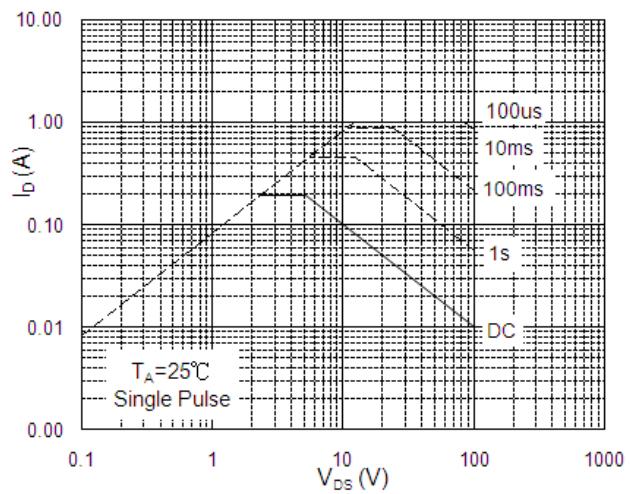
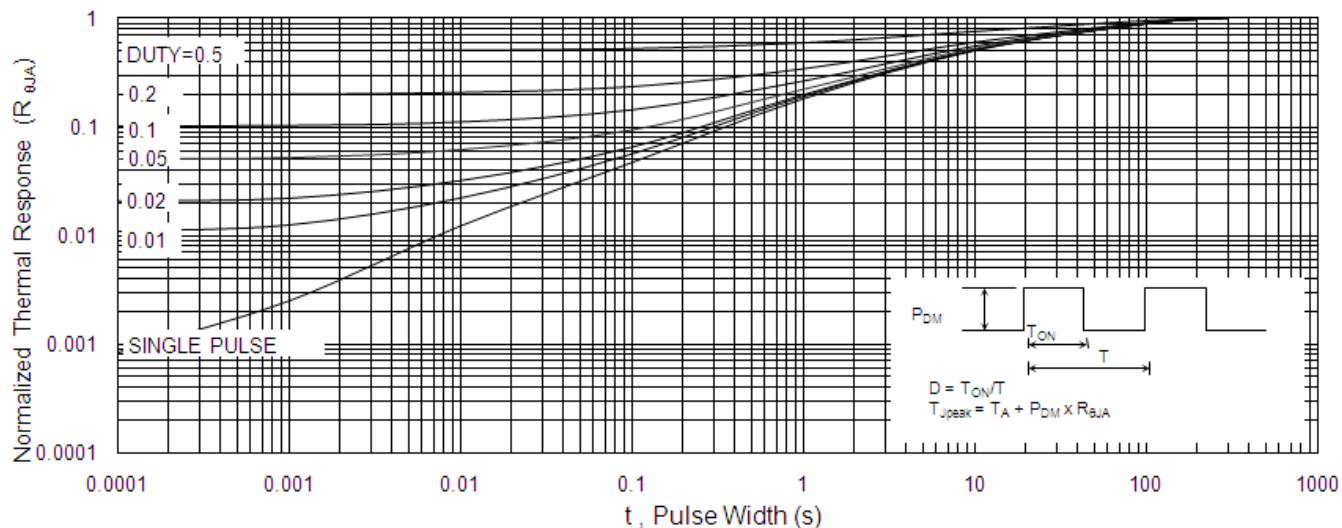
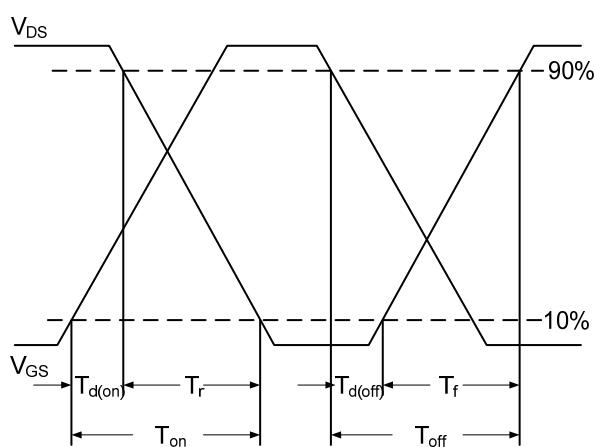
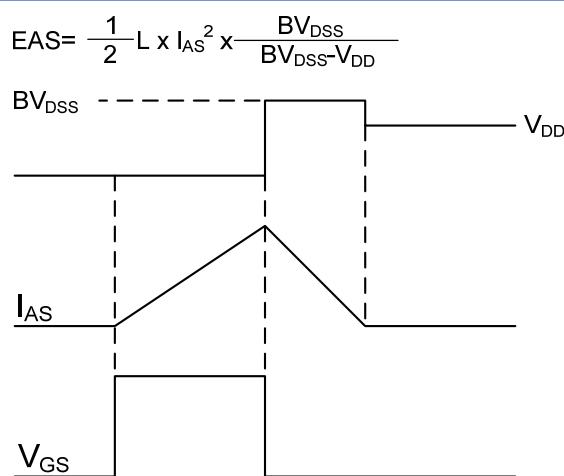


Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$

**N-Ch 650V Fast Switching MOSFETs**

**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Fig.10 Switching Time Waveform**

**Fig.11 Unclamped Inductive Switching Waveform**